



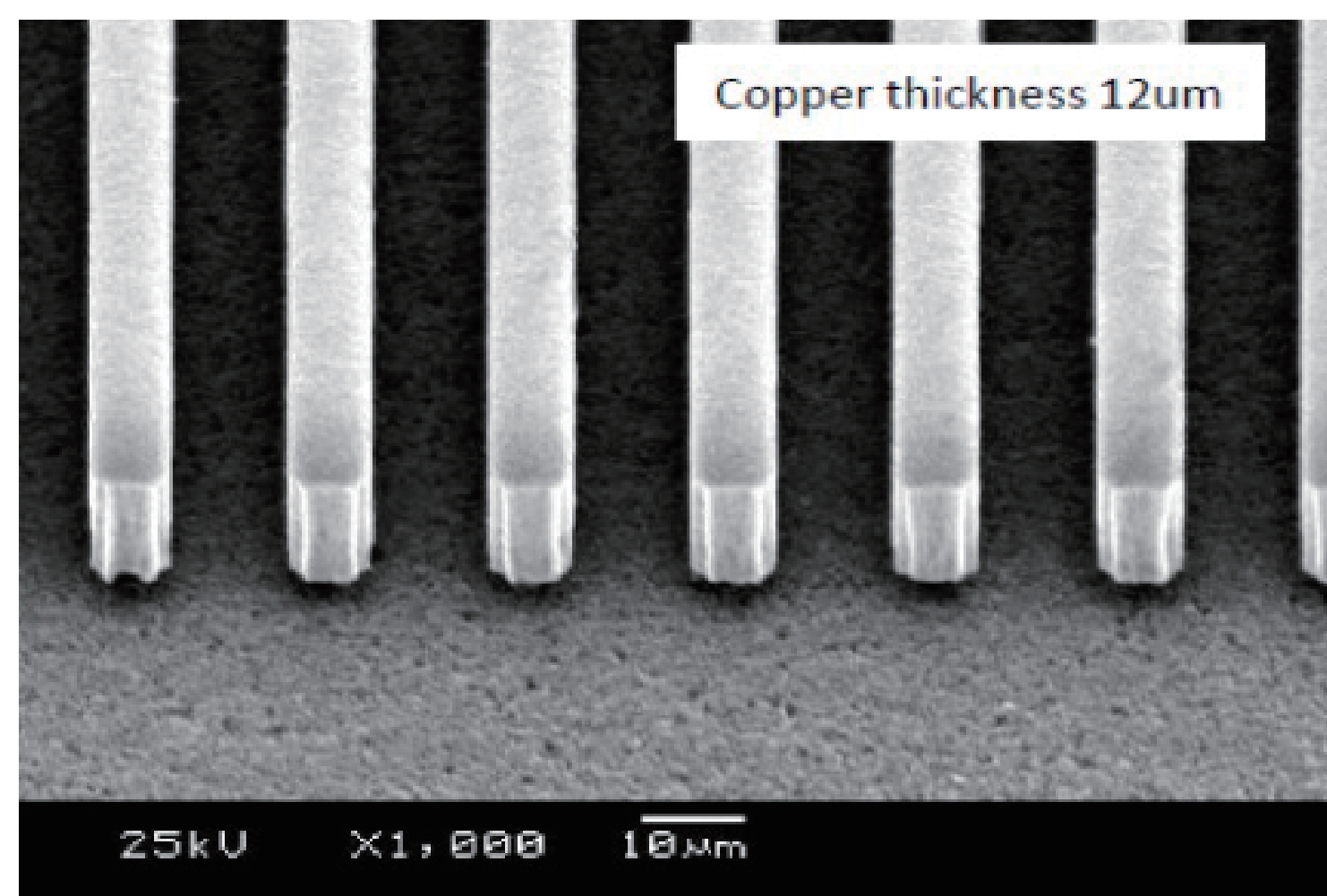
熱硬化型層間絶縁材料 Zaristo Series

Thermal curable Build up Material

(1) Zaristo125 / Zaristo 517 X (Thermal curable Dry film for SAP)

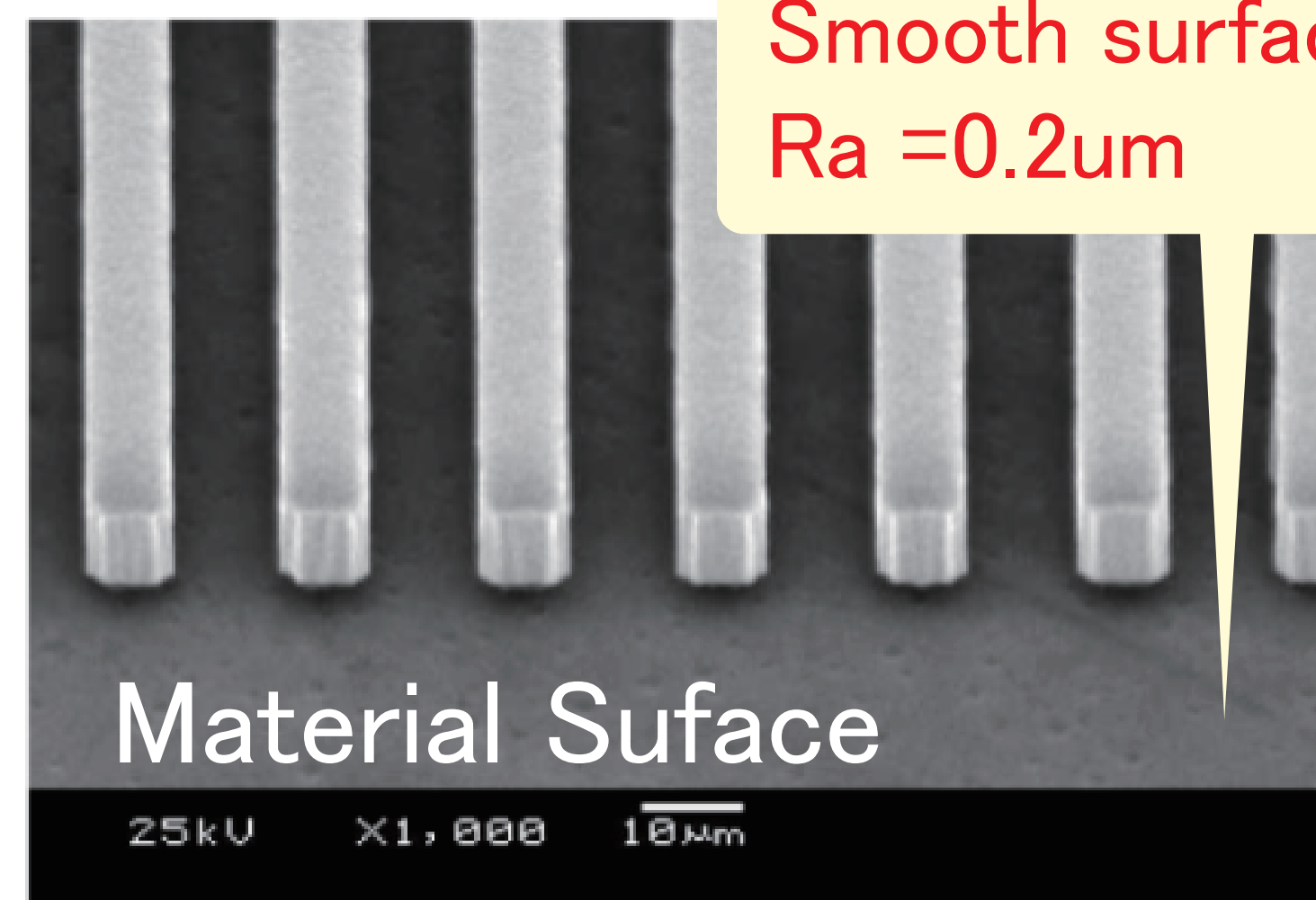
特徴 Features

- SAP対応 Suitable for Conventional SAP
- 高BHAIST耐性 Excellent LtL & L/S BHAIST stability



Zaristo 125

Fig. FLS(L/S=10/10um) on BUM



Zaristo 517X

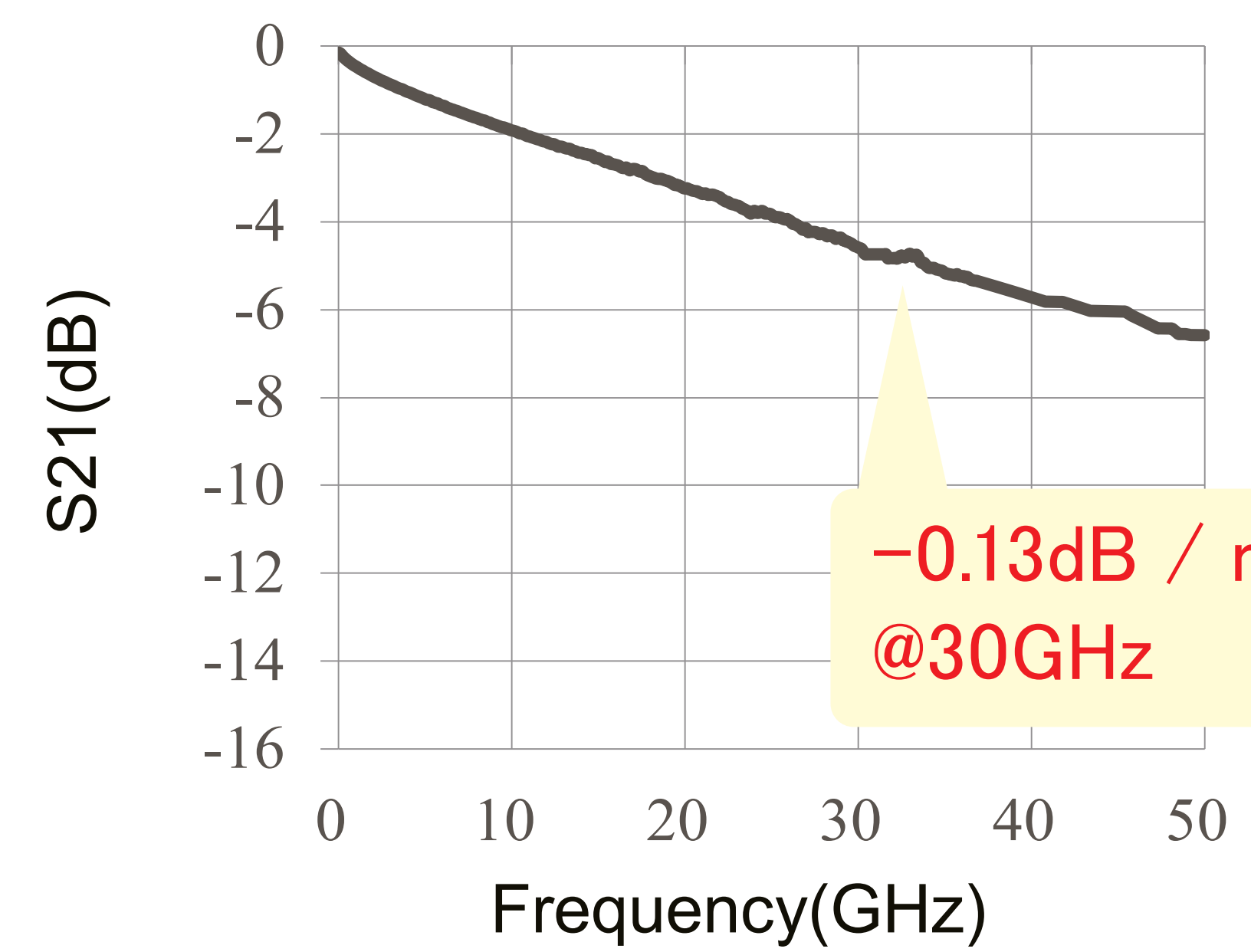


Fig. Transmission loss test of 517X

(2) Zaristo 907 (Thermal curable Dry film for MIS, ETS)

特徴 Features

- 超低反り Ultra Low Warpage after cure
- 低熱膨張&高弾性 Low CTE & High Modulus Dry film



Fig. Appearance after cure of 907

(3) Zaristo 700 series (Thermal curable High Dk Dry film)

特徴 Features

- 高Dk High Dk (Dk5~20の間で調整可能 We can adjust from Dk 5 to Dk 20.)
- 低Df Low Df (Below 0.009)

Properties List of Zaristo Series

Test Items	Zaristo125	Zaristo517X	Zaristo907	Zaristo700 series
Target Application Features	SAP for FC-CSP,BGA	Server ,High Speed Application	Coreless application (MIS,ETS)	Capacitor High Dk, Low Df
Tg(TMA)	165 -175°C	165 -175°C	140 -150°C	155-165°C
CTE α 1	25 - 30ppm	17ppm	8 - 10ppm	20 - 25ppm
Elastic Modulus	7 - 8GPa	11 - 12GPa	11.7Gpa	7.9 - 8.3GPa
Dk(10GHz)	3.4	3.4	3.6	5.0 - 18.0 Adjustable
Df(10GHz)	0.015	0.004-0.005	0.006-0.008	0.006-0.009
Peel strength Ra after Desmear	>5.0N/cm 0.25-0.40um	>4.0N/cm 0.2-0.3um	Under Evaluation	Incompatible



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